

G O D W I N G R U B E R

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VIA EXPRESS MAIL EL858166650US

Assistant Commissioner for Patents  
Washington, D.C. 20231-9998

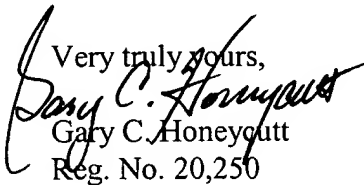
Re: Amendment 37 CFR 1.115  
Title: **WAFER SCALE ASSEMBLY OF CHIP-SIZE PACKAGES**  
Serial No.: 09/186,973  
Filing date: 11/05/98  
TI File No: TI-23158  
Our File No: 50000.2065

Dear Sir:

Enclosed please find the following items relating to the above-identified patent:

- (1) Amendment 37 CFR 1.115;
- (2) Replacement Pages;
- (3) Petition for Extension of Time; and
- (4) Postcards.

Please return the date-stamped postcard to our offices at the above address. In the meantime if you have any questions or comments concerning this matter, please call the undersigned at your earliest convenience. Otherwise, please accept the enclosed.

Very truly yours,  
  
Gary C. Honeycutt  
Reg. No. 20,250

GCH/ecc  
Enclosures  
cc: Lawrence Bassuk, Texas Instruments Incorporated